



Product Change Notification

Change Notification #: 118988-00
Change Title: Intel® Server System R2312WFTZSR
PCN 118988-00, Product Material,
New Alternate Hot Swap Backplane
Date of Publication: March 30, 2022

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*	April 14, 2022
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following change on the item listed in the “Products Affected” table.

Adding a second source for a Voltage Regulator (VR) controller on the Hot swap backplane (HSBP). The new controller is identical in function to the previous one but differs in form factor.

The interposer PCB supporting a new Programmable System-On-Chip (PSOC) is also being used in this version.

The new components have passed all functional and electrical validation tests successfully.

As a result, we are adding as alternate the following Hot swap backplane PBA: H88392-411

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers. Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
Intel® Server System R2312WFTZSR, Single	R2312WFTZSR	986053	M68658-001, K40015-015	H88392-351, H88392-352	M68658-002, K40015-016	H88392-351, H88392-352, H88392-411

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
March 30, 2022	00	Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

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